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O-Leading PCB, PCB 00 PCB 0000 (PCBA) 000 EMS 0000 0 00 000000 00 0000 000 HDI PCB, 0 0 PCB, 00-000 PCB 000 000 PCB 000 000000. 0000 00 00 0000 00 00 0 00 00000 000 0 00000. [000-00000 LED PCB 00](#))

00000, 0000 000 0000 0000 0000 00 00000000 : 00 00, 000000 00 0 00 00000 00000 00 00000 00000 00000 0000 00 O 0 0000 000000.

0000 O-leading 00 00 0000 0000 0000 00 00000 PCB 0 PCBA 0 00 00000 000000 00000 00 00000 00000 00000 0 00 0000 00 0 00000.

0000 0000 0000 00000000. [SMD LED 00 PCB 0000 00 12W](#)

O-LEADING
To Be Reliable, To Be Valuable
WE ALWAYS PROVIDE YOU
BEST HIGH DENSITY INTERCONNECT PCB

O-LEADING
To Be Reliable, To Be Valuable
WE ALWAYS PROVIDE YOU
BEST RIGID-FLEXIBLE CIRCUIT

O-LEADING
To Be Reliable, To Be Valuable

QUALITY IS OUR CULTURE



SOCOME C-877789



**Top Quality
Aluminum PCB**

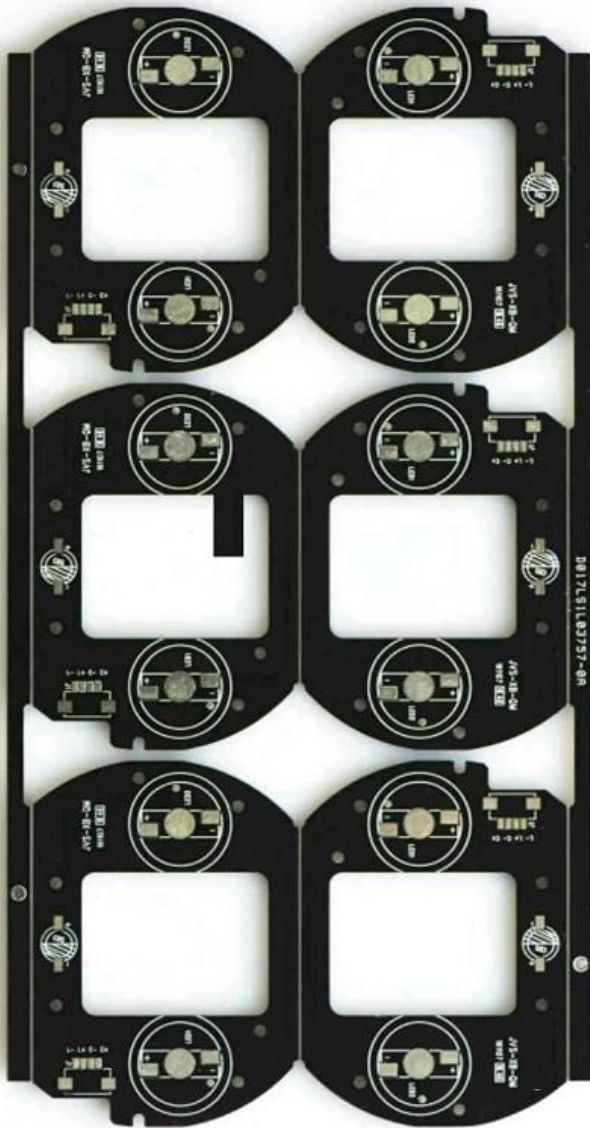






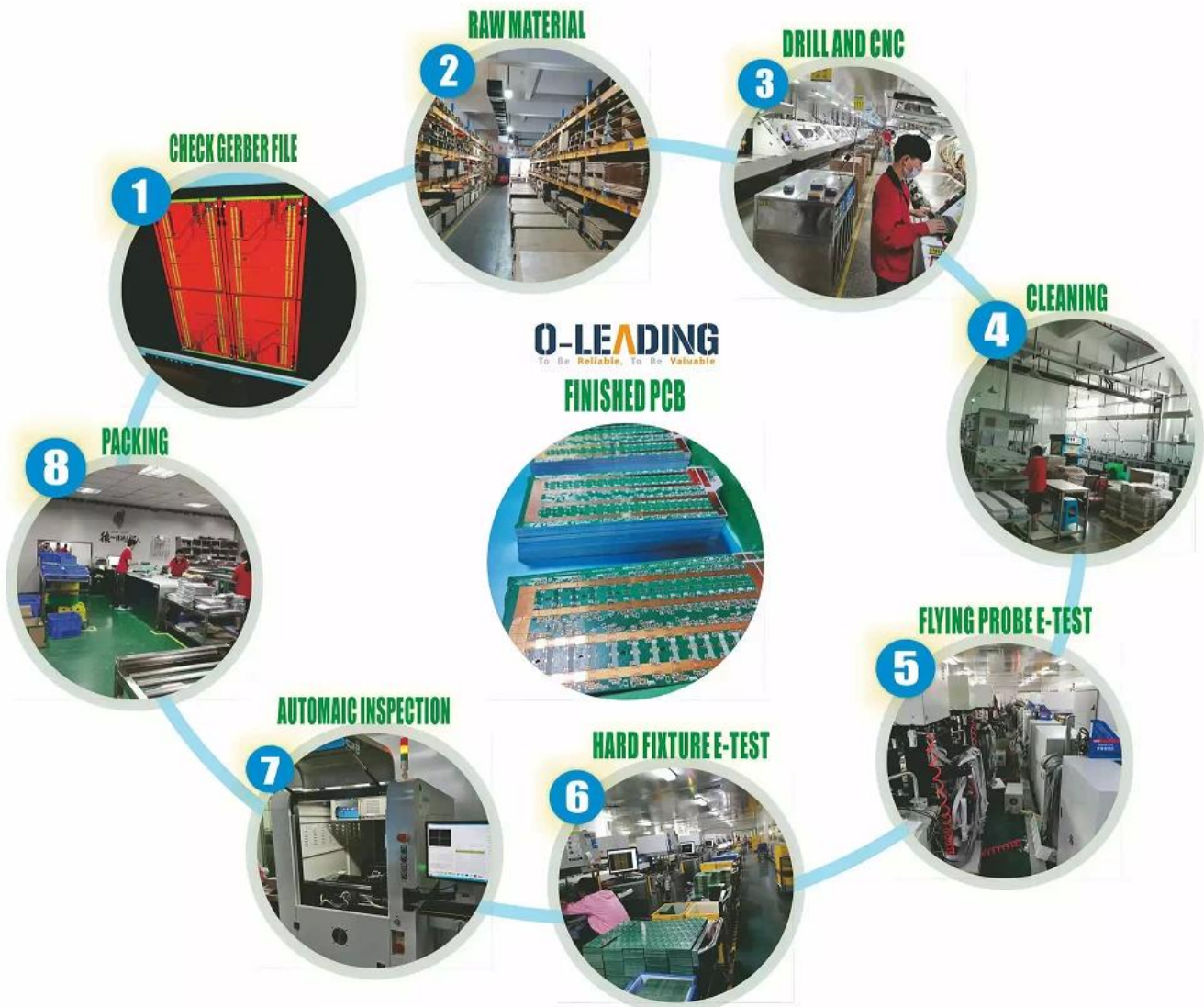






Production Process

18 years experience in one-stop PCB and PCBA, we can make your idea come true,



 CONSUMER ELECTRONICS

 AUTOMOTIVE ELECTRONICS

 INDUSTRIAL CONTROL

 INTELLECTUALIZED HOUSEHOLD CONTROL

 OTHER



30%
CONSUMER ELECTRONICS



18%
INTELLECTUALIZED HOUSEHOLD CONTROL

20%
AUTOMOTIVE ELECTRONICS



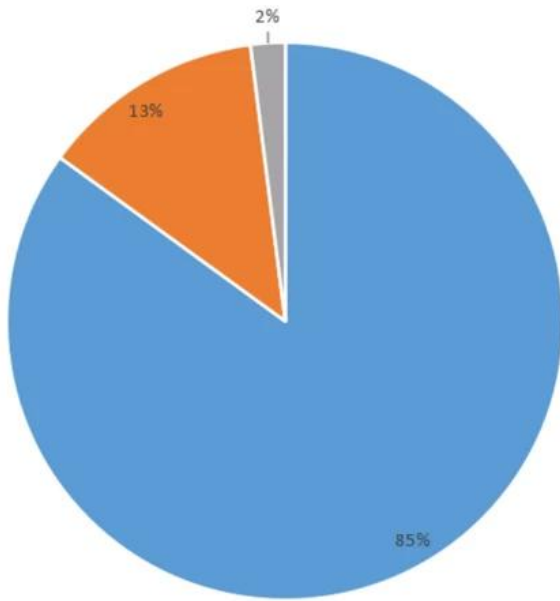
12%
OTHER



20%
INDUSTRIAL CONTROL



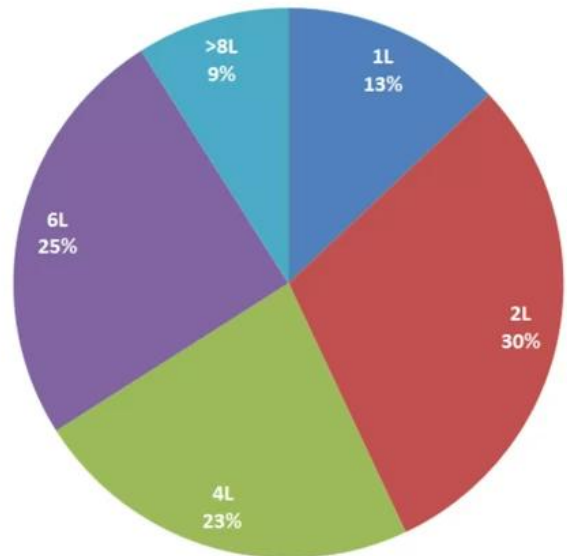
Product types



■ FR-4 PCB ■ MC PCB ■ rigid-flexible PCB

Product layers

■ 1L ■ 2L ■ 4L ■ 6L ■ >8L





Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT





CICC INSPECTION CERTIFICATION



嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R05

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No: 61691591-000-07-18-7

Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK

Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification
Sales of printed circuit boards

Initial issuance period: February 27, 2018
Renewal date: April 22, 2019
This certificate is valid during: April 22, 2019 – February 26, 2021
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
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The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the state. The effectiveness of this certificate shall be restricted to those activities which are covered by the certification. The actual information of this certification can be searched on the internet of CICC www.cicc.com.cn






CICC INSPECTION CERTIFICATION



嘉泰认证

质量管理体系认证证书

证书号: 18118Q10347R05

兹证明

诚领供应链(香港)有限公司

统一社会信用代码: 61691591-000-07-18-7

注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室

经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

建立的质量管理体系符合
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

认证范围
印刷线路板的销售

初次获证日期: 2018年02月27日
换证日期: 2019年04月22日
证书有效期: 自2019年04月22日至2021年02月26日
在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

第一次监督	第二次监督	黏贴处
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本证书认证范围不包括未取得有效的国家规定的行政许可、资质许可的产品/服务范围; 本证书通过CICC定期监督审核保持, 与年度《保持认证通知书》共同方为有效; 本证书信息可在国家认监委网站: www.cnca.gov.cn及CICC网站www.cicc.com.cn查询








Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

Table with 3 columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, 0/1. Lists various substances like Cadmium, Lead, Mercury, Hexavalent Chromium, Sum of PBBs, etc. with their respective limits and detection results.



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD
 ROOM 1205, 12/F
 TAI SANG BANK BLDG
 130-132 DES VOEUS ROAD
 CENTRAL, HONG KONG

E490354

Type	Cond Width			SS/ DS/ DSO	Max	Max			Meets UL796	C T	
	Min	Cond	Area		Solder	Flame	Class	DSR			
	Min	Edge			Thk						Limits
mm(in)	mm(in)	mic(mil)	Diam	C	sec	C	I				
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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PCB	
Layer Count	1-32
Weight	1 / 3oz-12oz
Prepreg / Core	3.0mil / 3.0mil
Prepreg / Core	4.0mil / 4.0mil
Aspect Ratio	10 : 1
Thickness	0.2mm-5.0mm
Panel Size (mm)	635 * 1500mm
Core Thickness	4mil
Plated Thickness	+/- 3mil
Blind / Buried Vias (All)	
Drill (mm, mil)	
Material	FR-4, FR-4high Tg, Epoxy, Polyimide, Copper, Aluminum
Surface Finish	HASL, OSP, ENIG, HAL-LF, Immersion Silver, Electroless Nickel

SMT	
PCB Material	FR-4, CEM-1, CEM-3, Epoxy, Polyimide
PCB Size	510x460mm
PCB Size	50x50mm
PCB Thickness	0.5mm-4.5mm
Drill Size	0.5-4mm
Drill Size	0201
Drill Size	0603
Drill Size	15mm
Drill Size	0.3mm
Drill BGA	0.4mm
Drill Size	+/- 0.03mm



Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days



1. O-Leading 1.1 1.2 1.3 1.4 1.5

- 1.1 ISO 9001 : 2008
- 1.2 X-ray, AOI (Automated Optical Inspector) ICT (in-circuit testing).
- 1.3 31 %
- 1.4 FR4, TG, Rogers, Arlon, Telfon, PI
- 1.5

2. O-Leading

10 (: ,) 31 %

3. O-Leading

FR4, TG, Rogers, Arlon, Telfon, PI

4. PCB 及 PCBA 的製造過程是什麼?

- 4.1 如何制定 BOM (Bill of Materials) : 物料清單, 物料清單表, 物料清單表.
- 4.2 PCB 的製造.
- 4.3 PCB 的組裝及 PCBA 的製造.
- 4.4 測試.
- 4.5 物料清單表, 物料清單表, 物料清單表.

5. PCB 的製造過程是什麼?

物料清單表 → 物料清單表 → 物料清單表 → PCB AOI → 物料清單表 → 物料清單表 → 物料清單表 → PTH → 物料清單表 → 物料清單表 → 物料清單表 → 物料清單表 → 物料清單表 → PCB AOI → 物料清單表 → 物料清單表 → 物料清單表 → 物料清單表 → E / T → 物料清單表.

6. HDI 的製造過程是什麼?

物料清單表, 物料清單表, 物料清單表 : 物料清單表, 物料清單表, VCP, 物料清單表, LDI, 物料清單表, 物料清單表, 物料清單表, 物料清單表 Mitsubishi, Hitachi, LDI, 物料清單表 Screen (Japan), 物料清單表 Hitachi, 物料清單表, 物料清單表, 物料清單表, 物料清單表.

7. O-lead 的製造過程是什麼?

O-lead 的製造過程 ENIG, OSP, LF-HASL, 物料清單表 (物料清單表 / 物料清單表), 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表. HDI 的製造過程 OSP, ENIG, OSP + ENIG, BGA PAD 物料清單表 0.3 mm 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表.

8. FPC 的製造過程是什麼? O-Leading 及 SMT 的製造過程是什麼?

O-Leading 的製造過程 8 物料清單表 FPC 物料清單表, 物料清單表, 物料清單表 2000mm * 240mm 物料清單表. 物料清單表 "Flex Capability" 物料清單表. 物料清單表 SMT 物料清單表, 物料清單表.

9. PCB 的製造過程是什麼?

- 物料清單表;
- 物料清單表;
- 物料清單表;
- 物料清單表;
- 物料清單表;
- 物料清單表;
- 物料清單表.

10. PCB, PWB 及 FPC 的製造過程是什麼?

物料清單表, 物料清單表. PWB (Printed Wire Board) 物料清單表, 物料清單表, 物料清單表. FPC Flexible Printed Board 物料清單表.

11. PCB 的製造過程是什麼?

物料清單表, 物料清單表, 物料清單表. 物料清單表 Tg 物料清單表, 物料清單表. 物料清單表 CTE 物料清單表, 物料清單表. 物料清單表 : 物料清單表 PCB 物料清單表 50 物料清單表 250 °C 物料清單表. 物料清單表; 物料清單表, 物料清單表 / 物料清單表, 物料清單表 PCB 物料清單表. 物料清單表 PCB 物料清單表, 物料清單表, 物料清單表; 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表.

12. O-leading 的製造過程是什麼?

O-leading 的製造過程 PCB, FPC, PCB 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表. 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表, 物料清單表.

13. 物料清單表, 物料清單表, 物料清單表?

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